賽雅浆料
SRYEO PASTE

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Product Specification

Product:	**Conductive Silver Paste**
Part Number:	**01H-4900 Series**

Application Scope :

This product is suitable for use with tempered glass electrodes/heating.

Usage Conditions :

Substrate	General glass tempering
Printing	200-300 mesh screen printing
Leveling	Let it level at room temperature for 5-15 minutes (adjust time based on actual leveling conditions).
Drying	Bake in a ventilation oven at 100-150°C for 10-15 minutes (the test temperature should not exceed 300°C; the baking time may be adjusted based on actual conditions).
Firing Condition	1.The sintering temperature is 600~750°C (recommended value) and the sintering time is 9-11 minutes. The sintering range can be adjusted between 600-800°C as required. 2. Can be formed simultaneously with the glass fiber reinforced plastic (FRP) during tempering at 600-750°C
Thinner	ST-1000

Characteristics :

	01H-4903	01H-4904	01H-4905	01H-4906	01H-4907	01H-4908	01H-4909
Fineness(um)	≤5	≤5	≤5	≤5	≤5	≤5	≤5
Viscosity (pa.s)	120-180	120-180	120-180	120-180	120-180	120-180	120-150
Silver content（%）	80~85	75~80	70~75	65~70	60~65	55~60	50~55
Resistivity (mΩ/□)	≤3	≤5	≤7	≤10	≤15	≤20	≤30
Adhesion(N)	≥55	≥52	≥50	≥48	≥45	≥42	≥40

Standard	Test Method And Conditions
Fineness	FOG test
Viscosity	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R,10 rpm, with adjustable viscosity at 25±1°C according to user requirements.
Resistivity	The sintering film thickness is 8-12um. The sintering film thickness is 8-12um.
Adhesion Strength	Peel Test: 0.5mmφ Tin plated Cu wire soldered on 2mm×2mm Pad. Solder: 96.5Sn/0.5Cu Mildly activated flux used.

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-25°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.